

COMBINED DECLARATION/POWER OF ATTORNEY
FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled
SEMICONDUCTOR WIRING SUBSTRATE, SEMICONDUCTOR DEVICE, METHOD FOR TESTING SEMICONDUCTOR DEVICE, AND METHOD FOR MOUNTING SEMICONDUCTOR DEVICE, the specification of which

(check one) is attached hereto.

 X was filed on July 2, 2002 as
Application Serial No. 10/187,269.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with Title 37, Code of Federal Regulations, § 1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, § 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

Prior Foreign Application(s)	Priority Claimed
<u>2001-201950</u> (Number)	<u>JAPAN</u> (Country)
<u>03/07/2001</u> (Day/Month/Year Filed)	<u> X </u> Yes <u> </u> No
<u> </u> (Number)	<u> </u> (Country)
<u> </u> (Day/Month/Year Filed)	<u> </u> Yes <u> </u> No
<u> </u> (Number)	<u> </u> (Country)
<u> </u> (Day/Month/Year Filed)	<u> </u> Yes <u> </u> No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, § 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

(Appln. Serial No.)	(Filing Date)	(Status-patented, pending, abandoned)
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(Appln. Serial No.)	(Filing Date)	(Status-patented, pending, abandoned)
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I hereby appoint as my attorneys, with full power of substitution and revocation, to prosecute the patent application identified above and to transact all business in the U.S. Patent and Trademark Office connected therewith: Raphael V. Lupo (Reg. No. 28,363); Jack Q. Lever, Jr. (Reg. No. 28,149); Kenneth L. Cage (Reg. No. 26,151); Stanislaus Aksman (Reg. No. 28,562); Paul Devinsky (Reg. No. 28,553); Edward E. Kubasiewicz (Reg. No. 30,020), Michael E. Fogarty (Reg. No. 36,139); Brian E. Ferguson (Reg. No. 36,801); Robert W. Zelnick (Reg. No. 36,976); and Wilhlem F. Gadiano (Reg. No. 37,136).

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The undersigned hereby authorizes the U.S. attorneys named herein to accept and follow instructions from Maeda Patent Office as to any action to be taken in the Patent and Trademark Office regarding this application without direct communication between the U.S. attorney and the undersigned. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by the undersigned.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor Sadami TAKEOKA

Inventor's signature Sadami Takeoka Date September 11, 2002

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Full name of fourth inventor Masayoshi YOSHIMURA

Inventor's signature Masayoshi Yoshimura Date September 11, 2002

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* City and State, or City and Country for foreign inventors

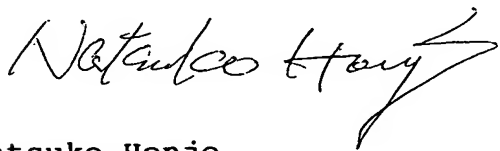
D E C L A R A T I O N

I, the undersigned, of 15-29 Tsukamoto, 3-chome, Yodogawa-ku, Osaka 532-0026, JAPAN, hereby certify that I am well acquainted with the English and Japanese languages, that I am an experienced translator for patent matter, and that the attached document is a true English translation of

U.S. Patent Application Serial No. 10/187,269 that was filed in Japanese.

I declare that all statements made herein of my own knowledge are true, that all statements on information and belief are believed to be true, and that these statements were made with the knowledge that willful statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code.

Signature:

A handwritten signature in cursive script, appearing to read 'Natsuko Honjo', with a long, sweeping flourish extending to the right.

Natsuko Honjo

Dated: September 11, 2002